

## General Description

The MY70N04NE5 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance.

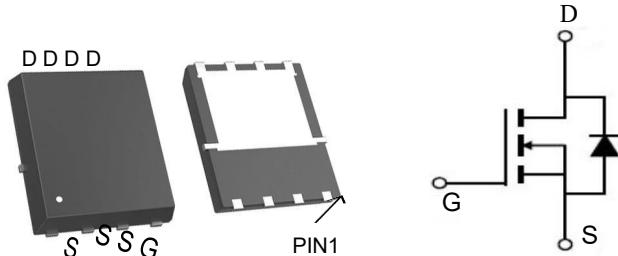


## Features

V <sub>DSS</sub>	40	V
I <sub>D</sub>	70	A
R <sub>DS(ON)</sub> (at V <sub>GS</sub> = 10V)	<7	mΩ
R <sub>DS(ON)</sub> (at V <sub>GS</sub> = 4.5V)	<10	mΩ

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY70N04NE5	PDFN5*6-8L	MY70N04NE5	5000

## Absolute Maximum Ratings (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	40	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>c</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	70	A
I <sub>D</sub> @T <sub>c</sub> =100 °C	Continuous Drain Current, V <sub>GS</sub> @ 10V	50	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	31	mJ
I <sub>AS</sub>	Avalanche Current	25	A
P <sub>D</sub> @T <sub>c</sub> =25 °C	Total Power Dissipation <sup>4</sup>	34.7	W
P <sub>D</sub> @T <sub>A</sub> =25 °C	Total Power Dissipation <sup>4</sup>	2	W
T <sub>S rn</sub>	Storage Temperature Range Operating	-55 to 150	°C
T <sub>J</sub>	Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	62	°C/V
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	3.6	°C/J

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	40	---	---	V
△BV <sub>DSS</sub> /△T <sub>J</sub>	BVDSS Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.034	---	V/°C
R <sub>DSON</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	---	7	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	---	---	10	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0	1.5	2.5	V
△V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.64	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =32V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fS</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =20A	---	36	---	S
R <sub>G</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	2.1	4.2	Ω
Q <sub>G</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =20V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A	---	10.7	---	nC
Q <sub>GS</sub>	Gate-Source Charge		---	3.3	---	
Q <sub>GD</sub>	Gate-Drain Charge		---	4.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =12V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3, I <sub>D</sub> =6A	---	8.6	---	ns
T <sub>r</sub>	Rise Time		---	3.4	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	25	---	
T <sub>f</sub>	Fall Time		---	2.2	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	1314	---	pF
C <sub>oss</sub>	Output Capacitance		---	120	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	88	---	
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	42	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	100	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V

Note :

1.The data tested by surface mounted on a 1 inch<sup>2</sup>FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=25V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=25A

4.The power dissipation is limited by 150°C junction temperature

5 .The data is theoretically the same as I<sub>O</sub> and I<sub>OM</sub> , in real applications , should be limited by total power dissipation.

### Typical Characteristics

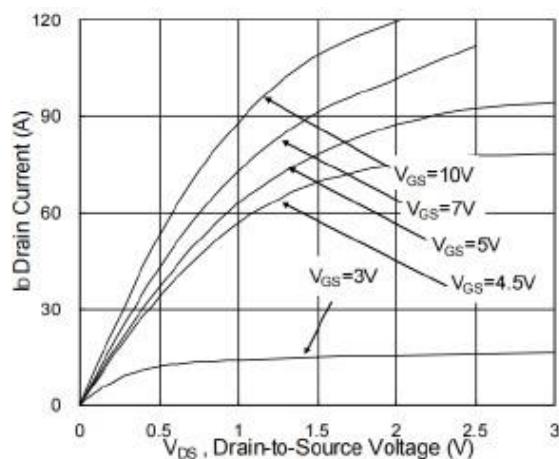


Fig.1 Typical Output Characteristics

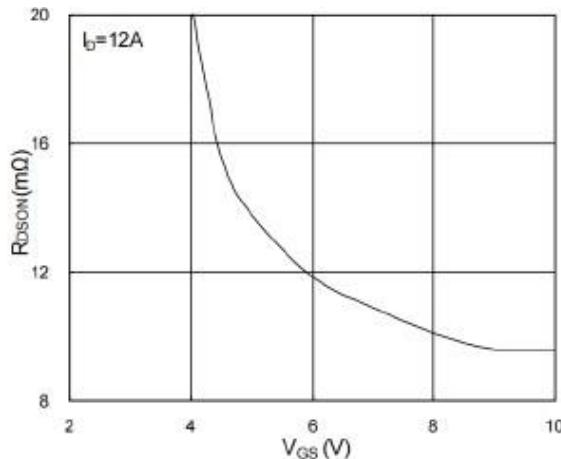


Fig.2 On-Resistance vs. G-S Voltage

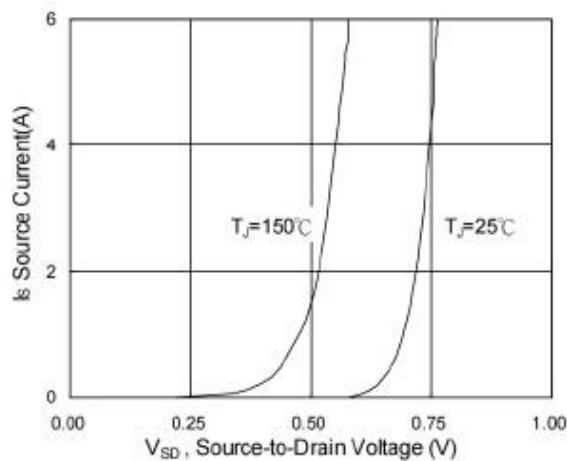


Fig.3 Forward Characteristics of Reverse

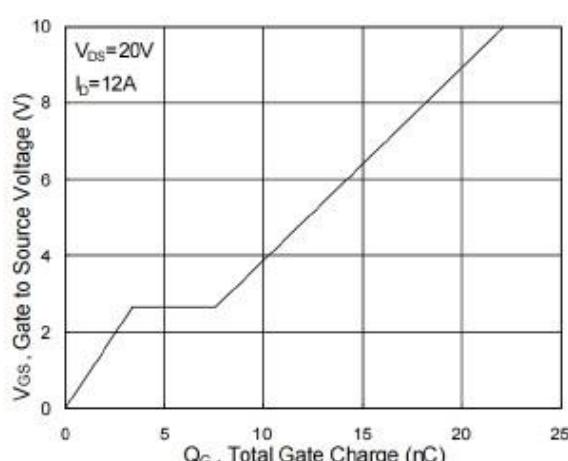
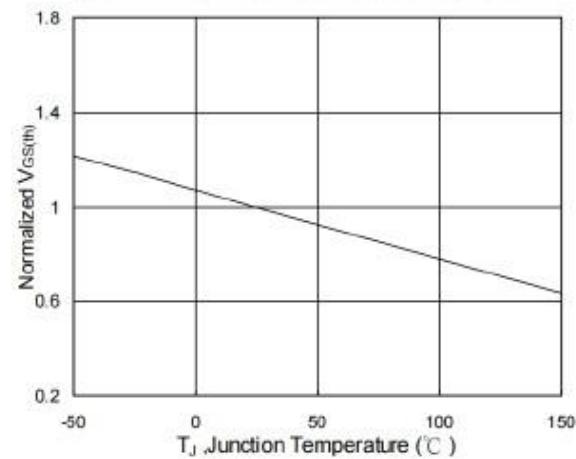
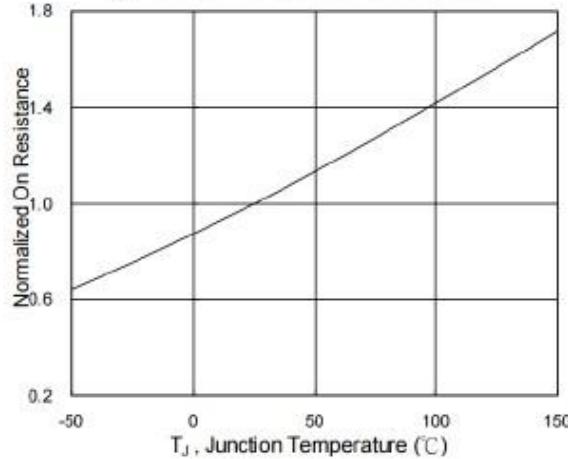


Fig.4 Gate-Charge Characteristics

Fig.5  $V_{GS(th)}$  vs.  $T_J$ Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

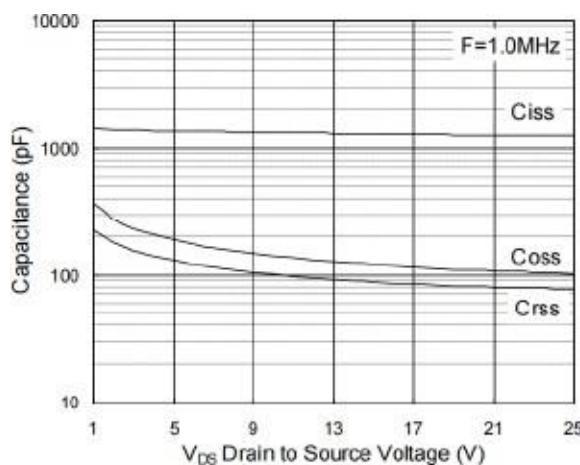


Fig.7 Capacitance

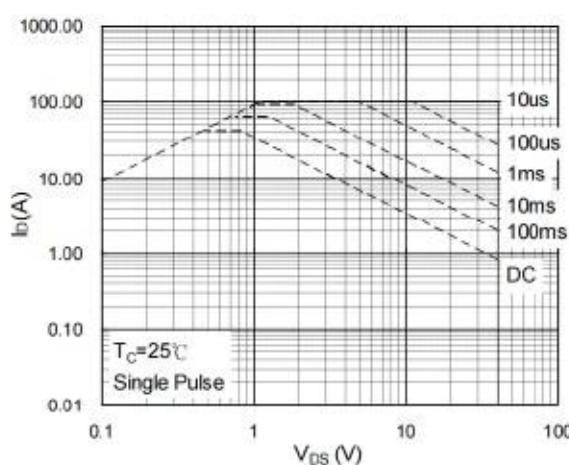


Fig.8 Safe Operating Area

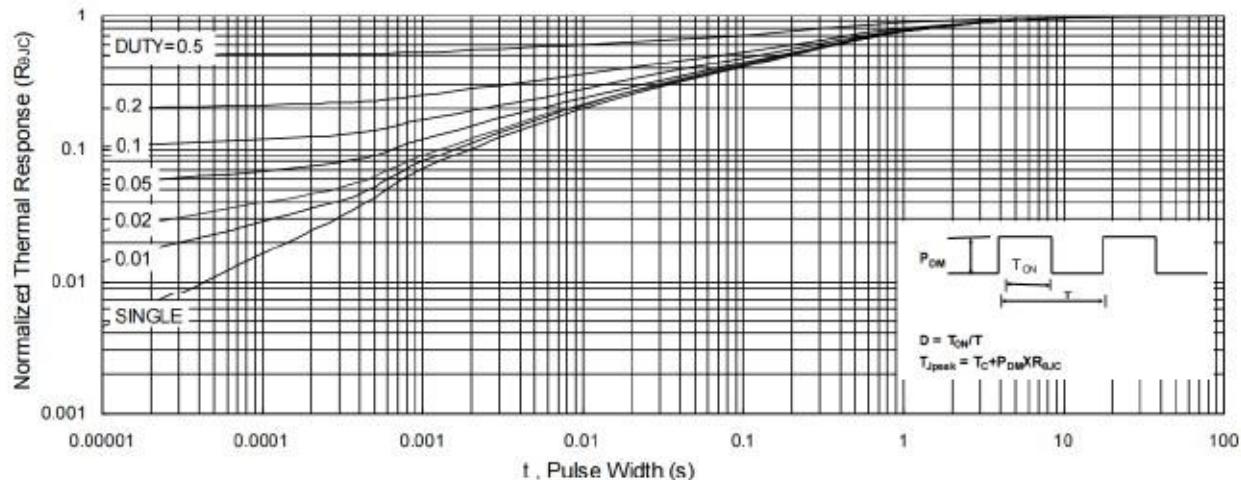


Fig.9 Normalized Maximum Transient Thermal Impedance

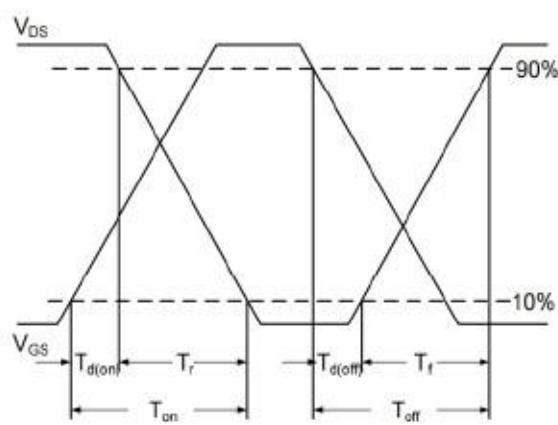


Fig.10 Switching Time Waveform

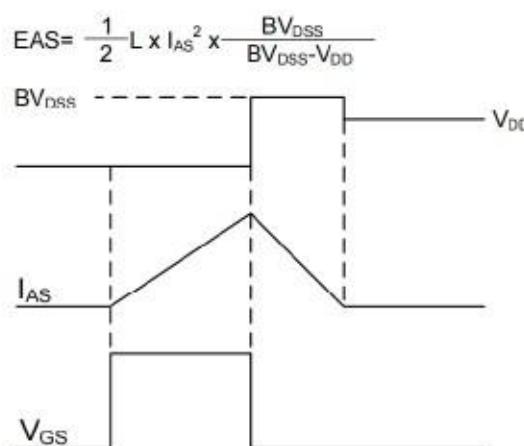
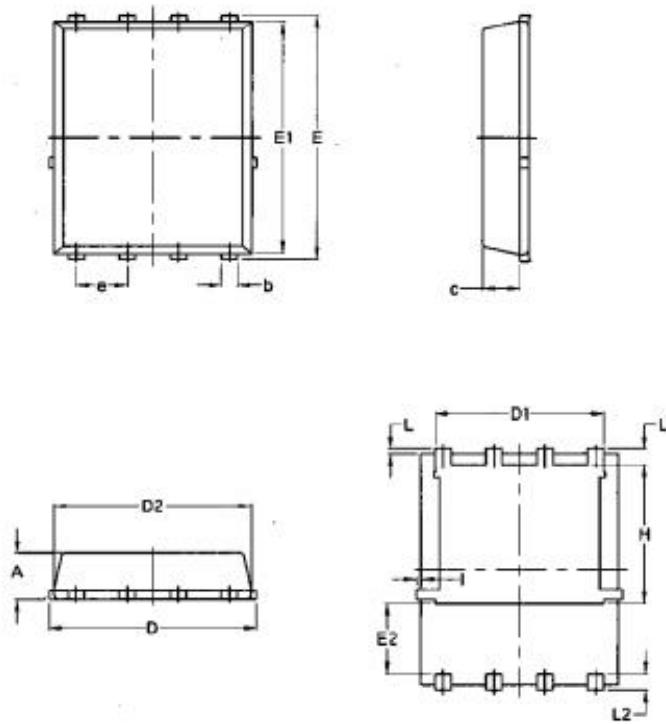


Fig.11 Unclamped Inductive Switching Waveform

### Package Mechanical Data-DFN5\*6-8L



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070